



Material Composition Declaration

EPC2030

Company Name	Efficient Power Conversion (EPC)	Issue Date:	3/14/2018
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	18.6 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	13.9274	74.8728	77.6906	748728
	Silicon oxide	7631-86-9	0.0739	0.3971		3971
	Silicon nitride	12033-89-5	0.0266	0.1429		1429
	Gallium nitride	25617-97-4	0.0887	0.4766		4766
	Aluminum	7429-90-5	0.1441	0.7745		7745
	Aluminum nitride	24304-00-5	0.0213	0.1148		1148
	Titanium	7440-32-6	0.0039	0.0211		211
	Titanium nitride	25583-20-4	0.0137	0.0737		737
	Copper	7440-50-8	0.0048	0.0257		257
	Tungsten	7440-33-7	0.0069	0.0371		371
	Polyimide		0.1403	0.7544		7544
Under Bump Metal	Titanium	7440-32-6	0.0017	0.0091	0.7707	91
	Nickel	7440-02-0	0.0000	0.0000		0
	Vanadium	7440-62-2	0.0000	0.0000		0
	Copper	7440-50-8	0.1417	0.7616		7616
Solder Bump	Tin	7440-31-5	3.8262	20.5695	21.5387	205695
	Silver	7440-22-4	0.1603	0.8615		8615
	Copper	7440-50-8	0.0200	0.1077		1077
Sum in total:			18.6015	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.